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Block Diagram

Page 3
50 Pin Connector to EVM Board, Hot Swap controller, EEPROM

Page 4
Isolated SPI & I2C, Isolated Fly buck Power Supply for +18V_ISO, -18V_ISO, +6V_ISO and 3.3V_NON_ISO

Page 5
LDO to generate +5V_ISO and VCC & ADC

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Analog Input 1

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Analog Input 2

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Mounting holes, Fiducials Marking

Revision History

Revision Notes
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Fiducials

Mounting holes

PCB Number: TIDA-00170
PCB Rev: E1

LOGO

PCB

Label Assembly Note

ZZ1

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive. ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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